



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Envy 23 TouchSmart All-in-One PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB, scalar, sidekey, webcam, b-cas, converterboard, Graphic card	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	7
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LED Panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Electric screw driver	2# X10
Description #2 Electric screw driver	1# X10

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- Please refer to the 3.1.2 disassemble hinge and real cover
- Please refer to the 3.1.3 disassemble the stand
- Please refer to the 3.1.4 Remove MB shielding
- Please refer to the 3.1.5 disassemble HDD & ODD
- Please refer to the 3.1.6 disassemble B-case
- Please refer to the 3.1.7 disassemble visa mount.
- Please refer to the 3.1.8 disassemble Speaker
- Please refer the 3.1.9/10/11 disassemble CPU/thermal module/system fan
- Please refer to 3.1.12/13 disassemble scalar & converter board.
- Please refer to 3.1.14 disassemble webcam
- Please refer to 3.1.15 disassemble microphone
- Please refer to 3.1.16 disassemble wireless card
- Please refer to 3.1.17 disassemble TV card.
- Please refer to 3.1.18 disassemble MB and battery remove
- Please refer to 3.1.19 disassemble CPU & DDR.
- Please refer to 3.1.20 disassemble Base pan and touch module.
- Please refer to 3.1.21 Remove Mouse/Keyboard Battery/MB
- Please refer to 3.1.22 Remove power supply

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 : Mechanical parts disassembly

- 1) Place the system

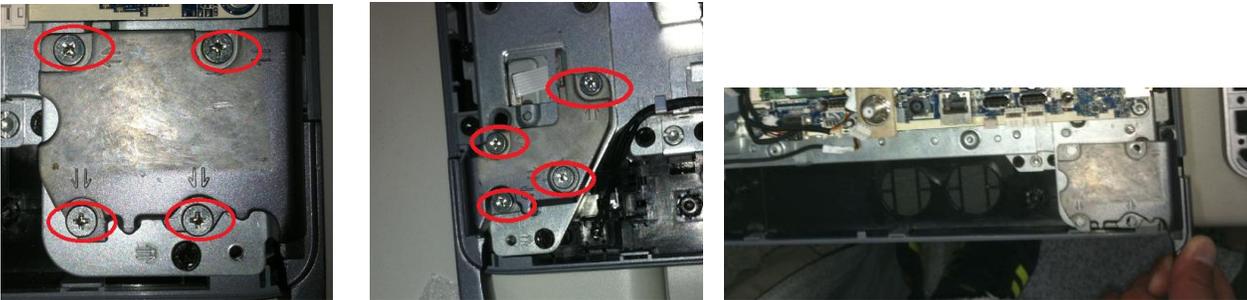


2) Disassemble hinge cover and rear cover.
Remove the screws with circle in red.



3) Disassemble stand

Remove four screws on both left and right so you can remove stand with two hands.



4) Disassemble MB shielding
Remove the screws with circles in red.

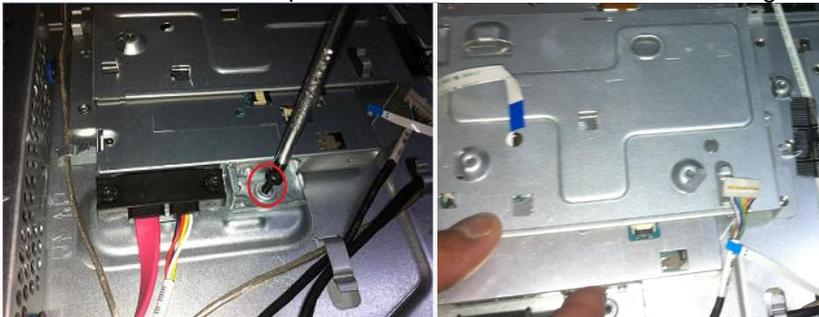


5) Disassemble HDD & ODD

Remove one screw from HDD and pull backward to disengage the HDD from base pan.

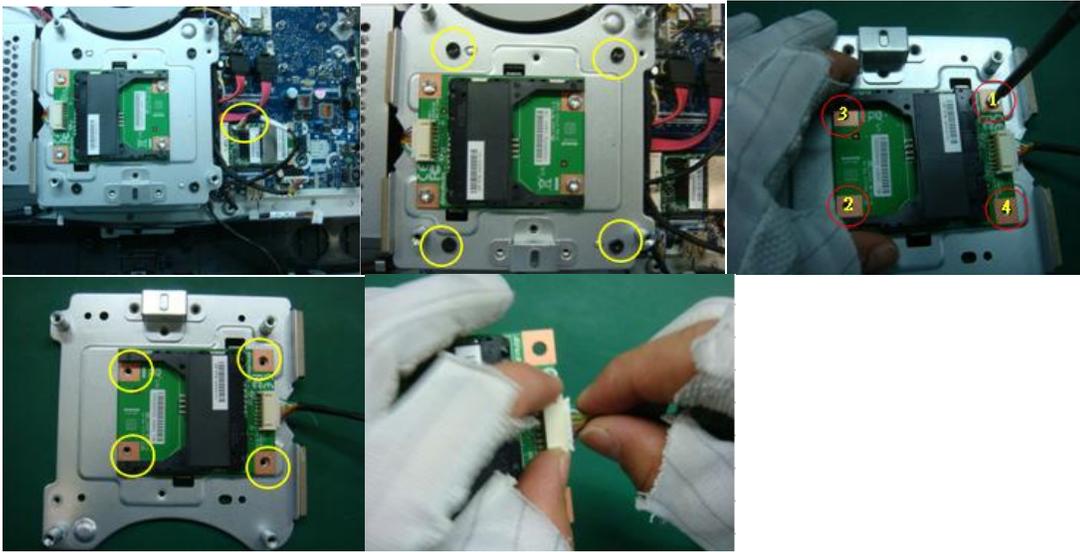


Remove one screw and push ODD forward to slide from ODD cage.



6) Disassemble B-case (with Japan SKU that has B-case module)

Remove the following screws that have circled in yellow



7) Disassemble for VESA mount (only for the scalar)
 Remove the following screws that have circled in red.



8) Disassemble speaker

Remove two screws from left and right. Also remove the speaker cable in order to take out two speakers from system.



9) Disassemble CPU thermal module

Remove five screws and remove away the thermal module.



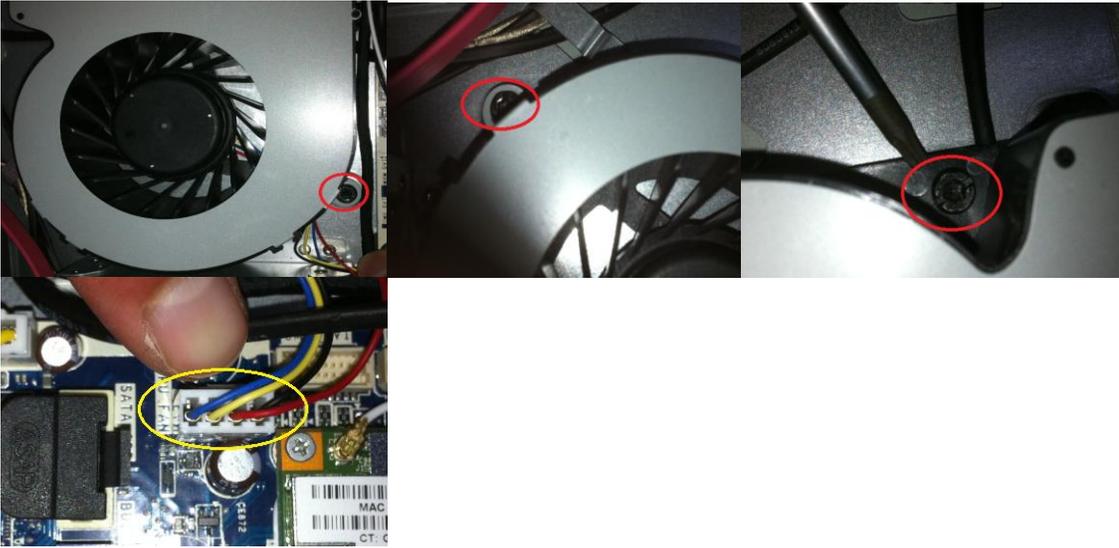
10) Disassemble MXM thermal module and remove the graphic card (with Graphic card module)

Remove five screws to remove the thermal module and disengage the graphic card from slot.

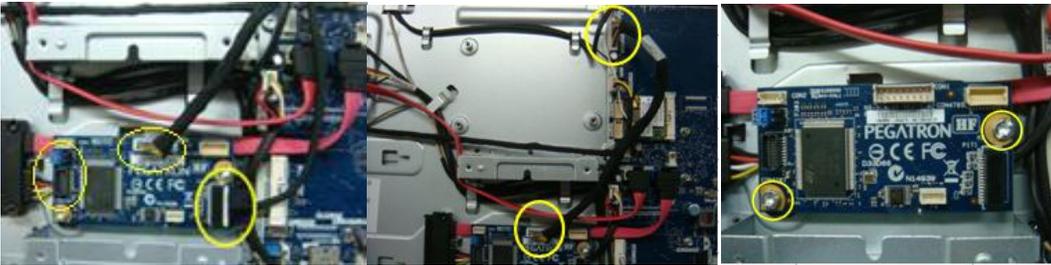


11) Disassemble FAN

Remove three screws and remove one cable to disassemble the fan.



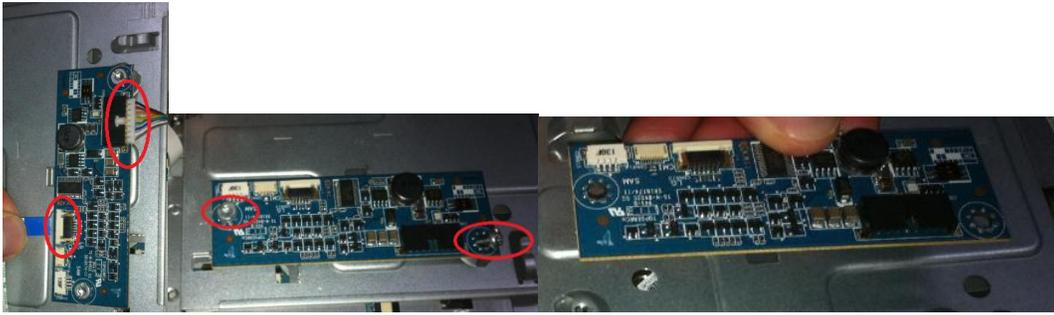
12) Disassemble Scalar Board (that has scalar SKU) and side key.
 Remove the following screws and cables that have circulated in yellow



13) Disassemble Converter board

Remove two cable and screws to disassemble the CVB.

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 Template Revision B



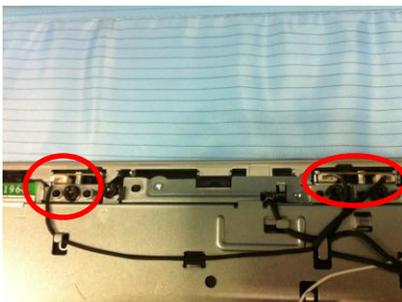
14) Disassemble webcam

Remove the cable and screw in order to disengage the webcam module and mechanical parts.



15) Disassemble MIC.

Remove the cable and screw in order to disengage the MIC module and mechanical parts.



16) Disassemble Wireless card

Remove one screw and two cables in order to remove wireless card.



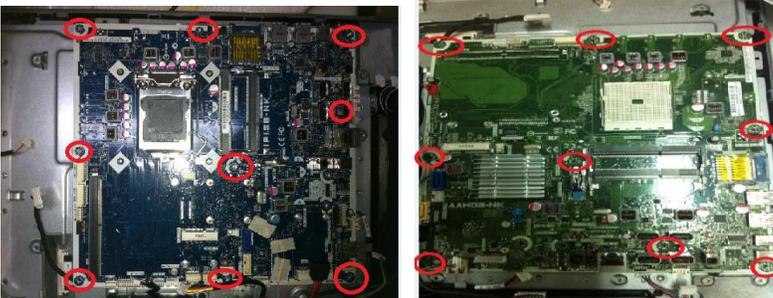
17) Remove TV card

Remove one screw and two connectors to remove the TV card.

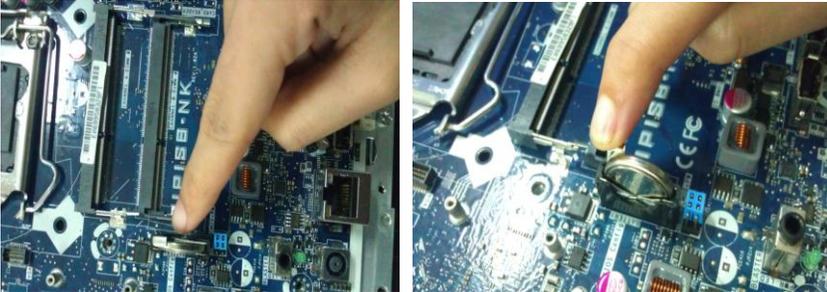


18) Remove MB & MB battery

Remove 9 screws to disassemble the INTEL/AMD MB.



Pull backward the clip to release the battery



19) Disassemble CPU and DDR

Remove the CPU by releasing the hook for Intel (above) & AMD (below).



Pull both clicks outward that holding the memory to remove the DDR



20) Separate BASE pan and touch module

Un-plug cable from touch control board(Left/Bottom)side.

Remove screws *4 to disassemble LCM and front bezel



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Remove Screws M3 x5 from LCM to disassemble LCD bracket.



21) Remove Mouse/Keyboard Battery/MB



22) Remove power supply

